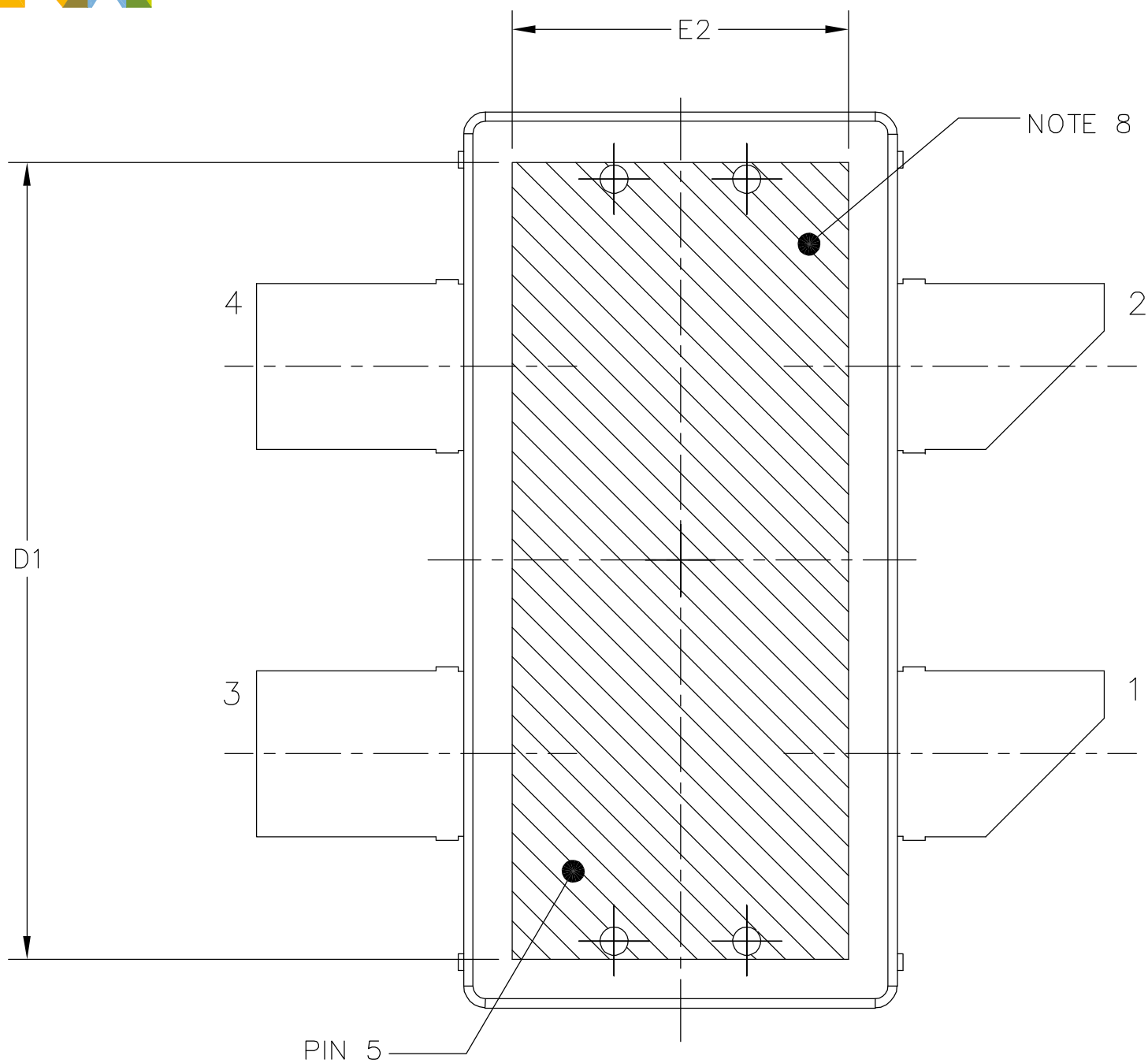


© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: OM780-4 STRAIGHT LEAD	DOCUMENT NO: 98ASA10833D REV: B	
	STANDARD: NON-JEDEC	
	SOT1818-4 16 MAR 2016	



BOTTOM VIEW
VIEW G-G

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE	
TITLE: OM780-4 STRAIGHT LEAD		DOCUMENT NO: 98ASA10833D	REV: B
		STANDARD: NON-JEDEC	
		SOT1818-4	16 MAR 2016



NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT TOP OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE TOP OF THE PARTING LINE.
4. DIMENSIONS "D" AND "E1" DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS .006 PER SIDE. DIMENSIONS "D AND "E1" DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .005 TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. DIMENSION A1 APPLIES WITHIN ZONE "J" ONLY.
8. HATCHING REPRESENTS THE EXPOSED AREA OF THE HEAT SLUG. THE DIMENSIONS D1 AND E2 REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF EXPOSED AREA OF HEAT SLUG.
9. DIMPLED HOLE REPRESENTS INPUT SIDE.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	0.148	.152	3.76	3.86	b	.147	.153	3.73	3.89
A1	.059	.065	1.50	1.65	c1	.007	.011	0.18	0.28
D	.808	.812	20.52	20.62	e	.350 BSC		8.89 BSC	
D1	.720	----	18.29	----	e1	.721	.729	18.31	18.52
E	.762	.770	19.36	19.56	aaa	.004	0.10		
E1	.390	.394	9.91	10.01					
E2	.306	----	7.77	----					
E3	.383	.387	9.72	9.83					
F	.025 BSC		0.635 BSC						
© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED				MECHANICAL OUTLINE			PRINT VERSION NOT TO SCALE		
TITLE: OM780–4 STRAIGHT LEAD						DOCUMENT NO: 98ASA10833D REV: B			
						STANDARD: NON–JEDEC			
						SOT1818–4			